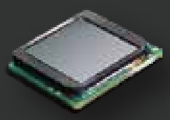
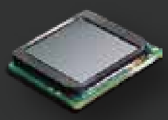
GLOBAL
SENSOR
TECHNOLOGY

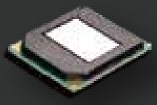
WLP Uncooled Infrared Detectors

Designed for Emerging Markets and Infrared Applications Popularization

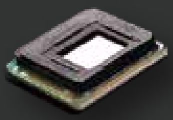
—12μm—


GST612W


GST412W


GST212W

—17μm—


GST417W

Wafer level packaging (WLP) is the process of completing high vacuum packaging directly on the entire MEMS wafer, then scribing and cutting to make a single infrared detector. WLP IR detectors are just designed to meet the miniaturization and low cost requirement in the application of infrared technology to consumer electronics market. Global Sensor Technology, with volume fabrication capability, is now offering a variety of WLP infrared module solutions to boost more new applications of emerging markets.

- Predictive Maintenance
- Security& Monitoring
- Outdoors
- UAV Payload EST
- Health Diagnosis
- ADAS
- Intelligent Hardware
- Smart Building
- Smart Home
- AIoT

“Infrared function integrated at low cost”

- Volume production to achieve lower cost.

“Easier integration into terminal products”

- Super mini size， minimum to 16×14×2.6mm.
- Light weight＜1.5g.

“Optimal and sharp imaging”

- High sensitivity，NETD＜40mK.
- Frame rate up to 50/60Hz.

Model	GST612W	GST412W	GST212W	GST417W
Material	VOx			
Resolution	640x512	400x300	256x192	400x300
Pixel Pitch	12μm			17μm
Spectral Range	8-14μm			
NETD	<40mK			
Digital Output	Built-in 14 bits ADC			
Typical Responsivity	15mV/K			
Thermal Response Time	<12ms			
Frame Rate	50/60Hz			
Dimension(mm)	18x16x2.8		16x14x2.6	18x16x2.8
Weight	<1.5g			
Operation Temperature	-40°C ~ +85°C			

Specifications are subject to change without notice.

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